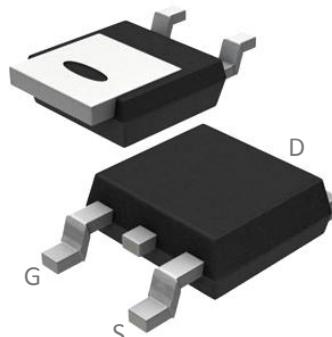


## P-Channel 60V (D-S) MOSFET

### Description:

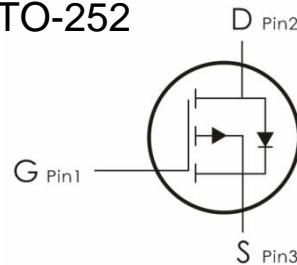
This P-Channel MOSFET uses advanced trench technology and design to provide excellent  $R_{DS(on)}$  with low gate charge. It can be used in a wide variety of applications.



### Features:

- 1)  $V_{DS}=-60V, I_D=-50A, R_{DS(on)}<20m\Omega @ V_{GS}=-10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low  $R_{DS(on)}$ .
- 5) Excellent package for good heat dissipation.

TO-252



### Absolute Maximum Ratings: ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain-Source Voltage	-60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current- $T_c=25^\circ C$	-50	A
	Continuous Drain Current- $T_c=100^\circ C$	-40	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	-280	A
$P_D$	Total Power Dissipation	270	W
$E_{AS}$	Single Pulsed Avalanche Energy	700	mJ
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	°C

### Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance,Junction to Case	0.46	°C/W

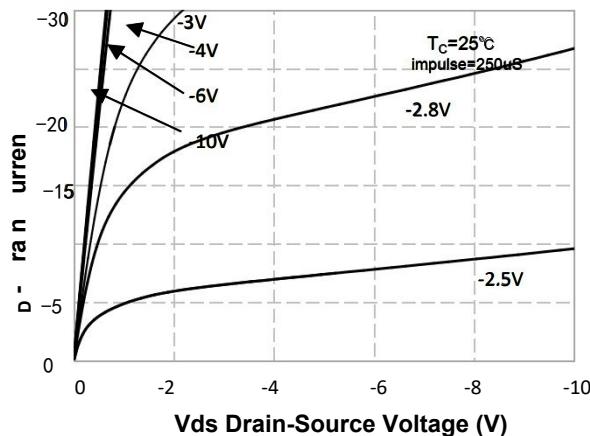
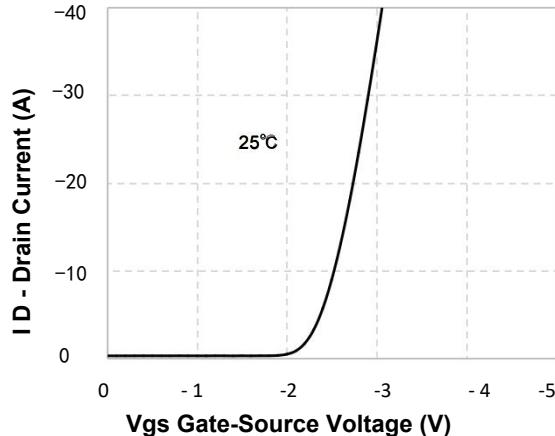
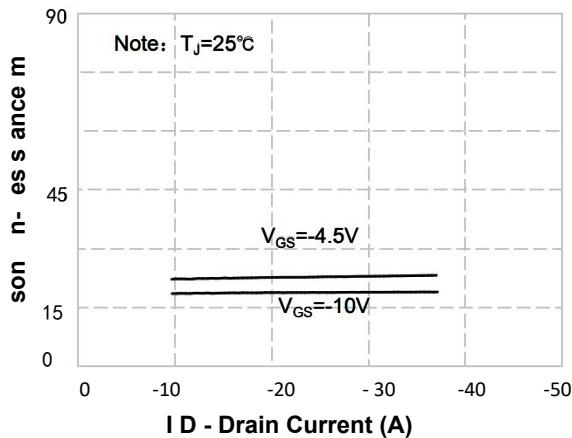
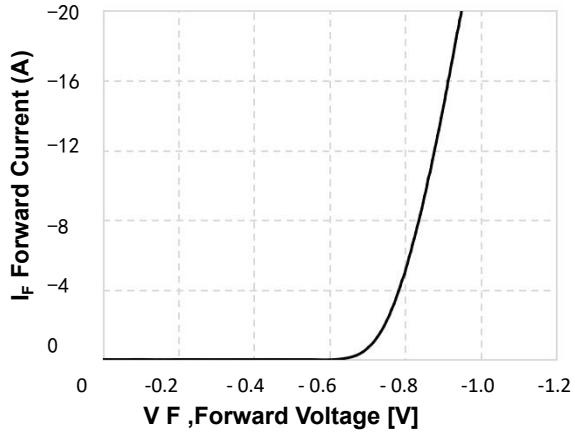
Electrical Characteristics: ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250 \mu\text{A}$	-60	---	---	V
$I_{\text{DS}}^{\text{SS}}$	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-60\text{V}$	---	---	-1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{A}$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=-250 \mu\text{A}$	-1.1	-1.6	-2.2	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-20\text{A}$	---	16.5	20	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-20\text{A}$	---	18.5	22	
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	4399	---	pF
$C_{\text{oss}}$	Output Capacitance		---	258	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	211	---	
<b>Switching Characteristics</b>						
$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-30\text{V}, I_{\text{D}}=-20\text{A}, V_{\text{GS}}=-10\text{V}, R_{\text{G}}=1\Omega$	---	23	---	ns
$t_r$	Rise Time		---	17	---	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time		---	55	---	ns
$t_f$	Fall Time		---	29	---	ns
$Q_g$	Total Gate Charge	$V_{\text{GS}}=-10\text{V}, V_{\text{DS}}=-30\text{V}, I_{\text{D}}=-20\text{A}$	---	114	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	27.3	---	nC
$Q_{\text{gd}}$	Gate-Drain "Miller" Charge		---	49	---	nC
<b>Drain-Source Diode Characteristics</b>						
$V_{\text{SD}}$	Drain Diode Forward Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-20\text{A}$	---	---	-1.2	V

<b>I<sub>S</sub></b>	Continuous Source Current	$V_G = V_D = 0V$	---	---	-50	A
<b>I<sub>SM</sub></b>	Pulsed Source Current		---	---	-280	A
<b>T<sub>rr</sub></b>	Reverse Recovery Time	$T_J = 25^\circ C, I_F = -20A, di/dt = 100A/\mu s$	---	117	---	nS
<b>Q<sub>rr</sub></b>	Reverse Recovery Charge		---	420	---	nC

**Notes:**

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition:  $T_J = 25^\circ C$ ,  $V_{DD} = -25V$ ,  $V_G = -5V$ ,  $R_G = 25\Omega$ ,  $L = 0.5mH$ ,  $I_{AS}$
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 0.5\%$

**Typical Characteristics:** ( $T_c = 25^\circ C$  unless otherwise noted)**Figure 1. On-Region Characteristics****Figure 2. Transfer Characteristics****Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage****Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**

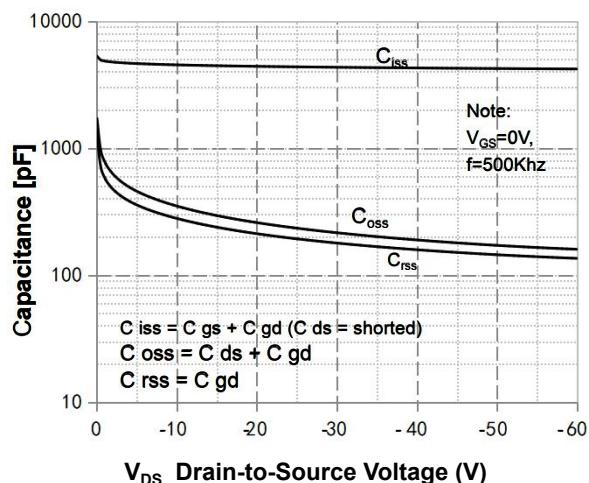


Figure 5. Capacitance Characteristics

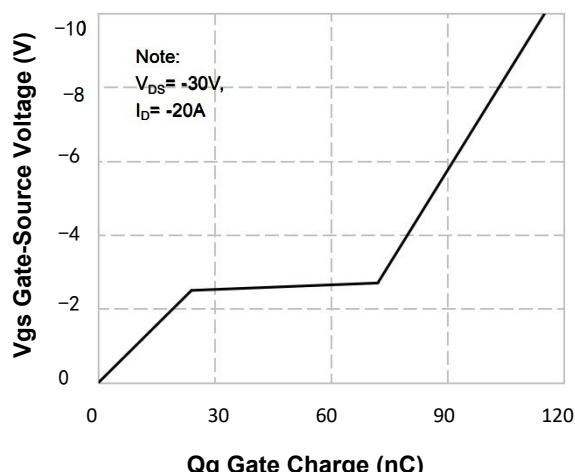


Figure 6. Gate Charge Characteristics

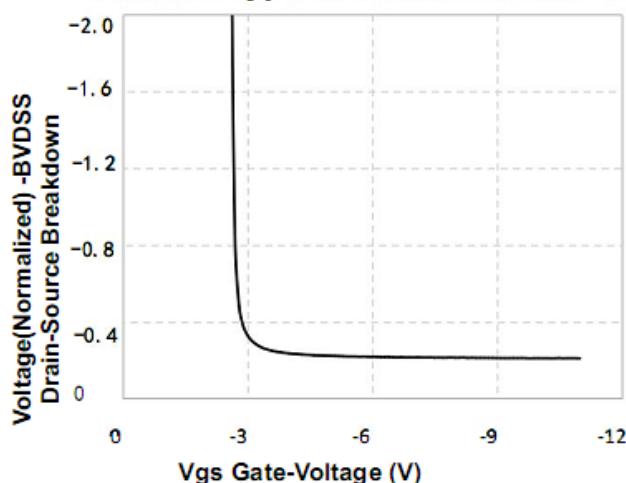


Figure 7. Breakdown Voltage Variation vs Gate-Voltage

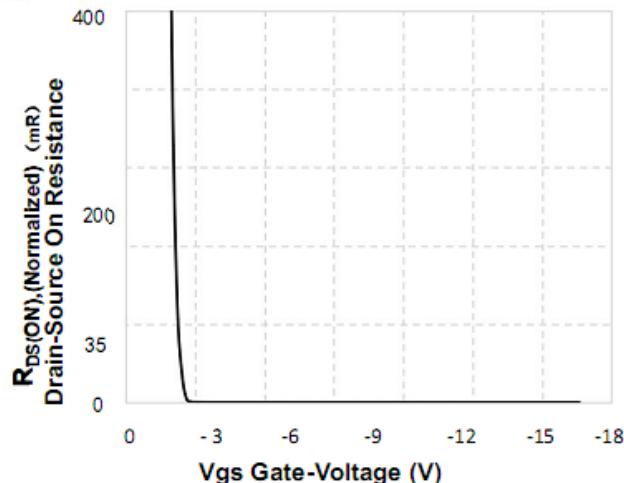


Figure 8. On-Resistance Variation vs Gate Voltage

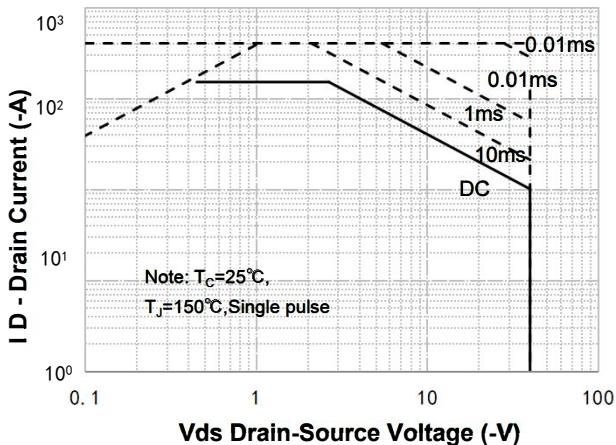


Figure 9. Maximum Safe Operating Area

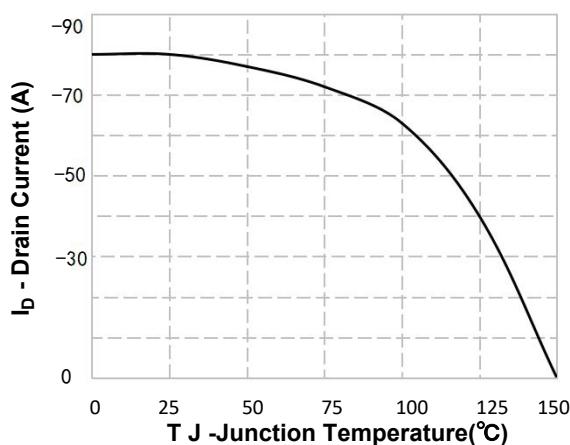


Figure 10. Maximum Continuous Drain Current vs Case Temperature

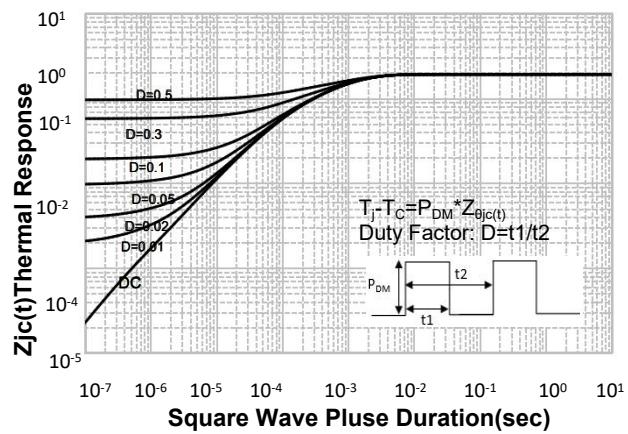


Figure 11. Transient Thermal Response Curve

**TO-252 Package Dimensions**

UNIT: mm

SYMBOL	min	nom	max	SYMBOL	min	nom	max
A	6.40		6.60	D	2.90		3.10
A1	5.20		5.40	D1	0.45		0.55
A2	4.40		4.60	D2	0.45		0.55
A3	4.40		4.60	e		2.30	
A4	0		0.15	E	2.20		2.40
A5	4.65		4.95	F	0.45		0.55
B	5.90		6.20	G		1.70	
B1	1.57		1.77	L	1.40		1.60
C	0.90		0.96	$\theta$ (度)	0		10.00

